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This application is a continuation-in-part of Serial No. 08/217,211, filed March 24, 1994, which is assigned to the assignee of the present application.--

2. As filed in the Request for File Wrapper Continuing Application of March 17, 1997, please delete before the first line of the specification:

--This application is a Continuation of Serial No. 08/350,168, filed November 30, 1994, now abandoned.--

3. Please amend the specification by inserting before the first line, the sentence:

--This application is a Continuation of Serial No. 08/350,168, filed November 30, 1994, now abandoned.--

IN THE CLAIMS:

Please add the following new claims 51-55:

--51. An electric device comprising:

an insulating substrate;

an active matrix circuit including at least one thin film transistor formed over

a first surface of said insulating substrate;

a driving circuit including at least another one thin film transistor for driving the active matrix circuit formed over said first surface of the insulating substrate;

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at least one semiconductor integrated circuit chip disposed over said first surface of the extended portion of the insulating substrate and operationally connected with the driving circuit wherein said integrated circuit chip is at least one of a memory, an input port, a correction memory and a CPU,

wherein said at least one thin film transistor and said at least another one thin film transistor are formed from a common semiconductor film formed over the first surface of the insulating substrate, and

wherein said at least one thin film transistor of the active matrix circuit has at least one lightly doped drain between a channel region and a drain region thereof.

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52. The device of claim 51 wherein the semiconductor integrated circuit chip is connected with the driving circuit by a wire bonding.

53. The device of claim 51 wherein the semiconductor integrated circuit chip is connected with the driving circuit by a COG (chip on glass).

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54. The device of claim 51 wherein the insulating substrate comprises a glass substrate